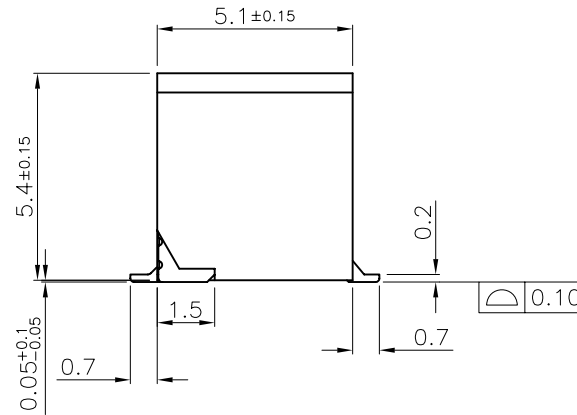
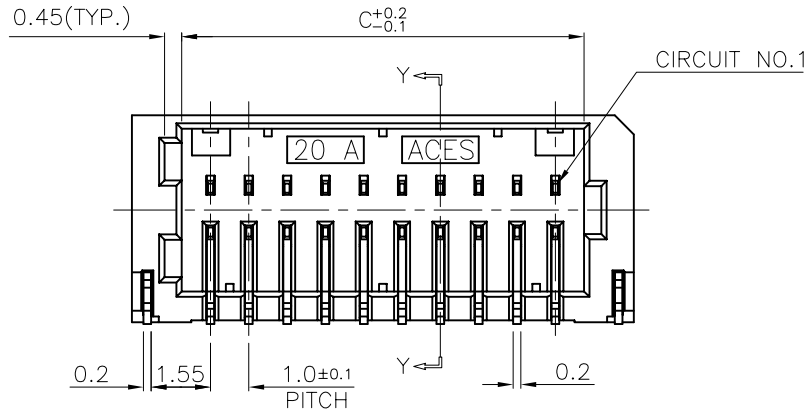


PCB PATTERN LAYOUT



- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
UNDERPLATING: 50~100u" NICKEL OVERALL.
FINISH: SEE ORDER INFORMATION.
 - FITTING NAIL:
UNDERPLATING: 50~100u" NICKEL OVERALL.
FINISH: SEE ORDER INFORMATION.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50246-XXXXX-XXX
 - PACKAGE PLS. REFER TO 88107-XX0X-TRP
 - COPLANARITY 0.1MM MAX. BASE ON DATUM A
 - TRUE POSITION 0.1MM MAX. BASE ON DATUM B
 - "Halogen Free" product:
- PART NUMBER
P/N LEGEND
50246-XXX X X-XXX

NO OF CKT
PACKING
0:TAPE REEL
1:TUBE PACKAGE

XXX	MATERIAL&COLOR
001	HF & BLACK
002	HF & NATURAL

Plating
L:Lead Free(Pure Tin)
1:Gold Flash over all(Lead Free)
N:Matt Tin(Lead Free)
C:15u" Gold on contact area
(Lead Free)
T:10u" Gold on contact area
(Lead Free)

CKT	Dim A	Dim B	Dim C	狀態欄
8	3.0	7.1	4.5	v
10	4.0	8.1	5.5	v
12	5.0	9.1	6.5	v
16	7.0	11.1	8.5	v
18	8.0	12.1	9.5	v
20	9.0	13.1	10.5	v
24	11.0	15.1	12.5	v
30	14.0	18.1	15.5	v
34	16.0	20.1	17.5	v
40	19.0	23.1	20.5	v
50	24.0	28.1	25.5	v
60	29.0	33.1	30.5	v

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.		
檢驗尺寸標示 SYMBOLS ① ② INDICATE CLASSIFICATION DIMENSION ① MARK IS CRITICAL DIM. ② MARK IS MAJOR DIM.	品名 (TITLE) 1.0mm WTB WAFER SMT R/A D/R TYPE		製圖 (DR) 13/11/12 CANDY	
	圖號 (DWG NO.) 50246-XXXXX-XXX		審核 (CHKD) DAVID	
表面處理 (FINISH)		核准 (APPD) JERRY		
比例 (SCALE) 1:1	單位 (UNITS) mm	張數 (SHEET) 1 OF 1	SIZE A4	REV C